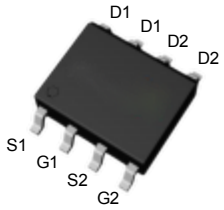
Features

- **N Channel**
  40V/15A,
  $R_{DS(ON)}$ = 8.5mΩ (typ.) @ V_{GS} = 10V
  $R_{DS(ON)}$ = 14mΩ (typ.) @ V_{GS} = 4.5V
- **P Channel**
  -40V/-15A,
  $R_{DS(ON)}$ = 15mΩ (typ.) @ V_{GS} =-10V
  $R_{DS(ON)}$ = 20mΩ (typ.) @ V_{GS} =-4.5V
- 100% UIS + R_g Tested
- Reliable and Rugged
- Lead Free Available (RoHS Compliant)

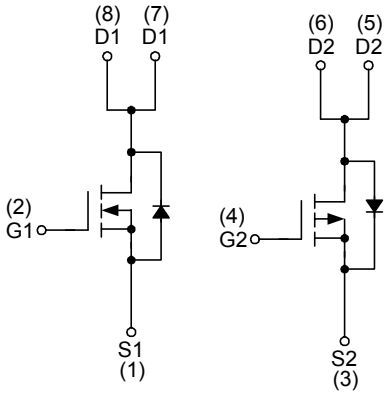
Applications

- Synchronous Rectification
- Motor Control
- Fan Pre-driver H-bridge

Pin Description



Top View of SOP-8



N-Channel MOSFET P-Channel MOSFET

Absolute Maximum Ratings (T_A = 25°C unless otherwise noted)

Symbol	Parameter			N Channel	P Channel	Unit
Common Ratings						
V_{DSS}	Drain-Source Voltage			40	-40	V
V_{GSS}	Gate-Source Voltage			±20	±20	V
T_J	Maximum Junction Temperature			150		°C
T_{STG}	Storage Temperature Range			-55 to 150		°C
I_S	Diode Continuous Forward Current			15	-15	A
I_{DP}	Pulse Drain Current Tested	V_{GS}=10V(N),V_{GS}=-10V(P)		45	-45	A
I_D	Continuous Drain Current		T_A=25°C	15	-15	A
			T_A=70°C	11.3	-11.3	
P_D	Maximum Power Dissipation		T_A=25°C	2	2	W
			T_A=70°C	1.3	1.3	
$R_{\theta JL}$	Thermal Resistance-Junction to Lead		Steady State	50	50	°C/W
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient		t ≤ 10s	62.5	62.5	°C/W
			Steady State [b]	110	110	
I_{AS} [a]	Avalanche Current, Single pulse		L=0.5mH	12	12	A
E_{AS} [a]	Avalanche Energy, Single pulse		L=0.5mH	36	36	mJ

Note a : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_j=25°C).
Note b : Surface Mounted on 1in^2 pad area, t =999sec.

N Channel Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	N Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=250μA	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=32V, V_{GS}=0V	-	-	1	μA
		T_J=85°C	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=250μA	1.0	1.8	2.5	V
I_{GSS}	Gate Leakage Current	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$ [c]	Drain-Source On-state Resistance	V_{GS}=10V, I_{DS}=6A	-	8.5	10	mΩ
		V_{GS}=4.5V, I_{DS}=5A	-	14	18	
Diode Characteristics						
V_{SD} [c]	Diode Forward Voltage	I_{SD}=1A, V_{GS}=0V	-	0.75	1.1	V
t_{rr}	Reverse Recovery Time	I_{DS}=6A, dI_{SD}/dt=100A/μs	-	13	-	ns
Q_{rr}	Reverse Recovery Charge		-	8.7	-	nC
Dynamic Characteristics [d]						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz	-	2.5	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=20V, Frequency=1.0MHz	-	590	-	pF
C_{oss}	Output Capacitance		-	110	-	
C_{rss}	Reverse Transfer Capacitance		-	85	-	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=20V, R_L=20Ω, I_{DS}=1A, V_{GEN}=10V, R_G=6Ω	-	7.8	-	ns
t_r	Turn-on Rise Time		-	6.9	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	22.4	-	
t_f	Turn-off Fall Time		-	4.8	-	
Gate Charge Characteristics [d]						
Q_g	Total Gate Charge	V_{DS}=20V, V_{GS}=10V, I_{DS}=6A	-	15.7	22	nC
Q_g	Total Gate Charge	V_{DS}=20V, V_{GS}=4.5V, I_{DS}=6A	-	7.5	10.5	
Q_{gth}	Threshold Gate Charge		-	1.85	-	
Q_{gs}	Gate-Source Charge		-	3.24	-	
Q_{gd}	Gate-Drain Charge		-	2.75	-	

Note c：Pulse test ; pulse width≤300μs, duty cycle≤2%.
Note d：Guaranteed by design, not subject to production testing.

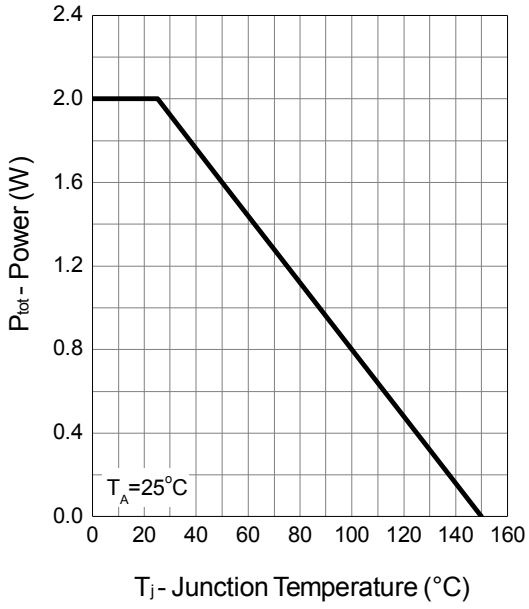
P Channel Electrical Characteristics (T_A = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	P Channel			Unit
			Min.	Typ.	Max.	
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_{DS}=-250μA	-40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-32V, V_{GS}=0V	-	-	-1	μA
		T_J=85°C	-	-	-30	mA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_{DS}=-250μA	-1.0	-1.8	-2.5	V
I_{GSS}	Gate Leakage Current	V_{GS}=±20V, V_{DS}=0V	-	-	±100	nA
$R_{DS(ON)}$ [c]	Drain-Source On-state Resistance	V_{GS}=-10V, I_{DS}=-5.5A	-	15	18	mΩ
		V_{GS}=-4.5V, I_{DS}=-3.5A	-	20	26	
Diode Characteristics						
V_{SD} [c]	Diode Forward Voltage	I_{SD}=-1A, V_{GS}=0V	-	-0.75	-1	V
t_{rr}	Reverse Recovery Time	I_{DS}=-5.5A, dI_{SD}/dt=100A/μs	-	15	-	ns
Q_{rr}	Reverse Recovery Charge		-	8	-	nC
Dynamic Characteristics [d]						
R_G	Gate Resistance	V_{GS}=0V,V_{DS}=0V,F=1MHz	-	8	-	Ω
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-20V, Frequency=1.0MHz	-	2150	-	pF
C_{oss}	Output Capacitance		-	315	-	
C_{rss}	Reverse Transfer Capacitance		-	285	-	
$t_{d(ON)}$	Turn-on Delay Time	V_{DD}=-20V, R_L=20Ω, I_{DS}=-1A, V_{GEN}=-10V, R_G=6Ω	-	7.8	-	ns
t_r	Turn-on Rise Time		-	7	-	
$t_{d(OFF)}$	Turn-off Delay Time		-	31	-	
t_f	Turn-off Fall Time		-	17	-	
Gate Charge Characteristics [d]						
Q_g	Total Gate Charge	V_{DS}=-20V, V_{GS}=-10V, I_{DS}=-5.5A	-	15	-	nC
Q_g	Total Gate Charge	V_{DS}=-20V, V_{GS}=-4.5V, I_{DS}=-5.5A	-	7.5	-	
Q_{gth}	Threshold Gate Charge		-	1.4	-	
Q_{gs}	Gate-Source Charge		-	2.4	-	
Q_{gd}	Gate-Drain Charge		-	3.5	-	

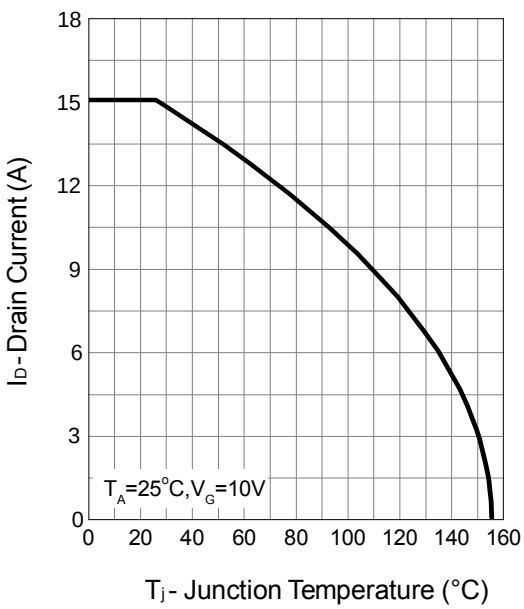
Note c：Pulse test; pulse width≤300μs, duty cycle≤2%.
Note d：Guaranteed by design, not subject to production testing.

N Channel Typical Operating Characteristics

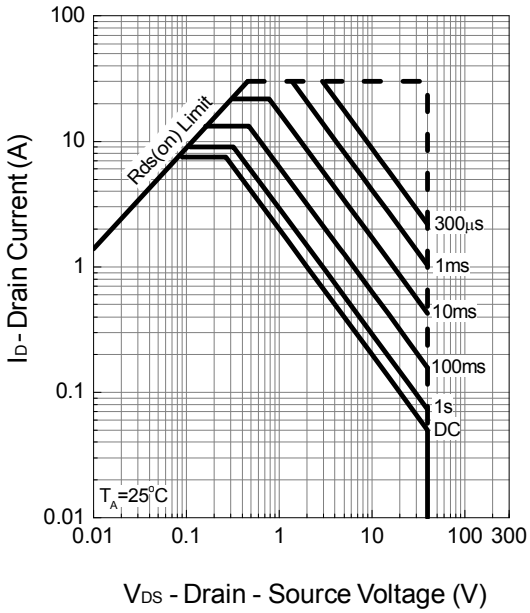
Power Dissipation



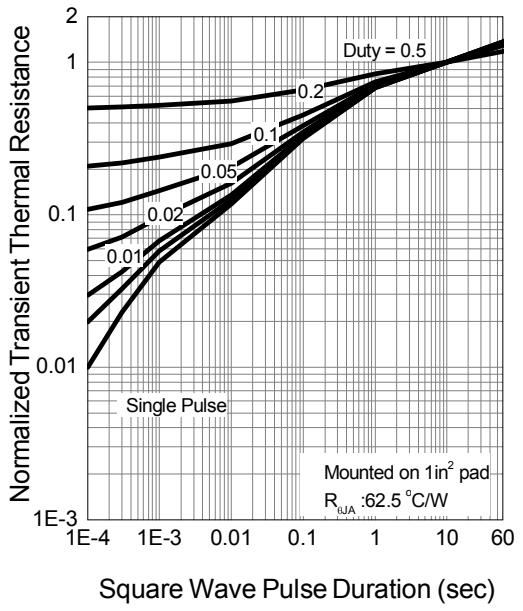
Drain Current



Safe Operation Area

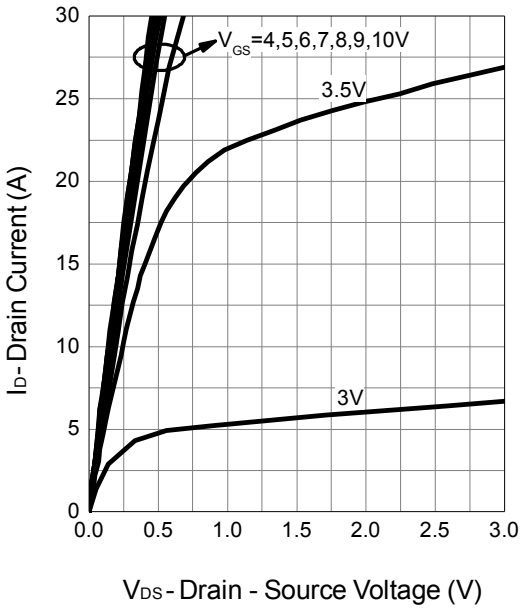


Thermal Transient Impedance

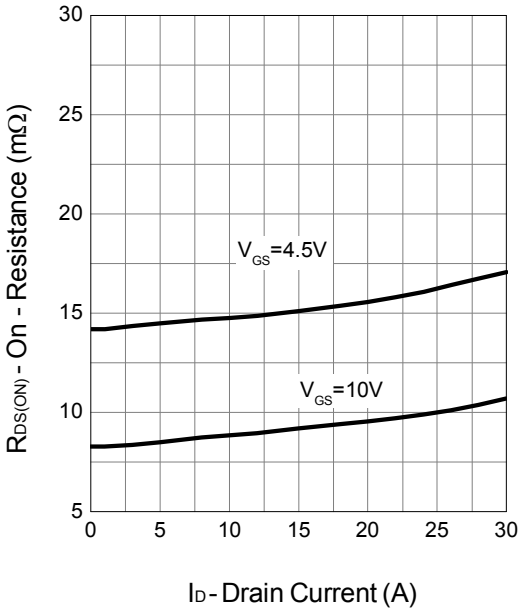


N Channel Typical Operating Characteristics (Cont.)

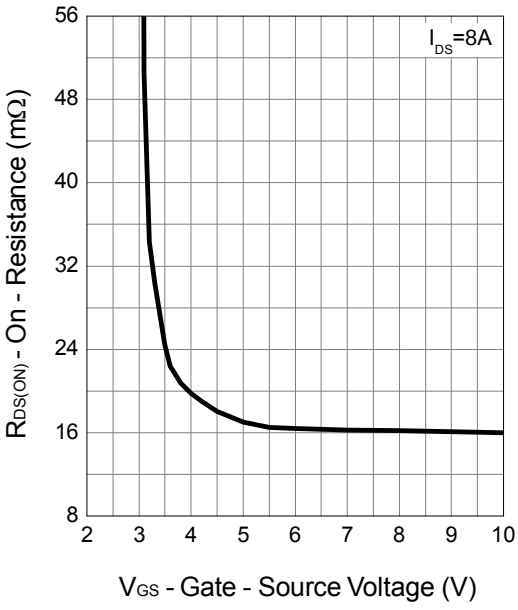
Output Characteristics



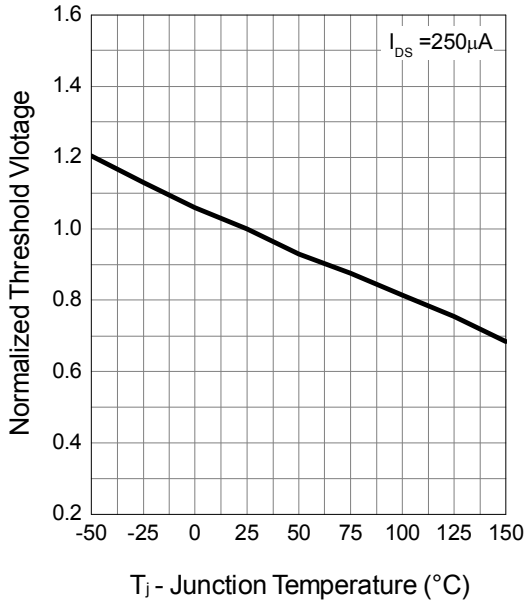
Drain-Source On Resistance



Gate-Source On Resistance

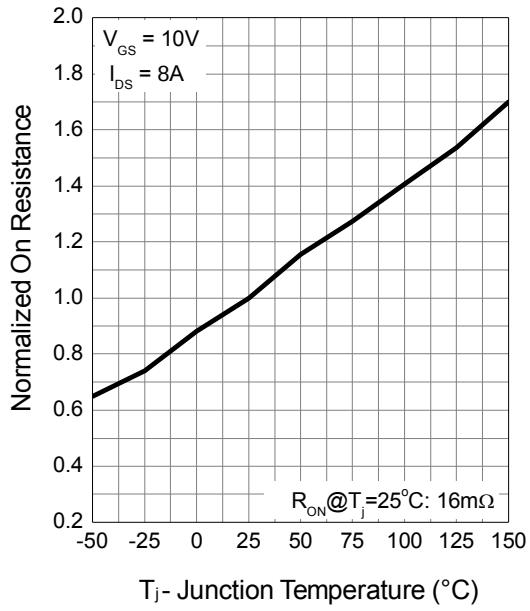


Gate Threshold Voltage

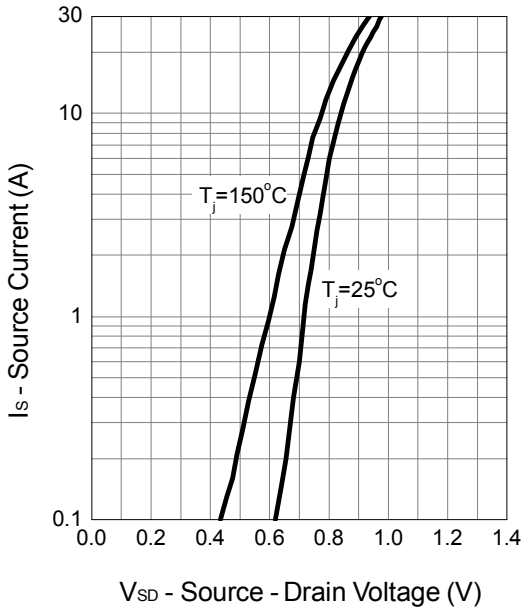


N Channel Typical Operating Characteristics (Cont.)

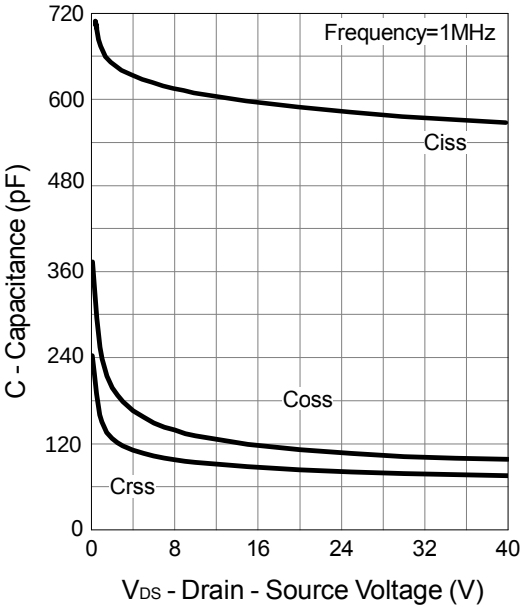
Drain-Source On Resistance



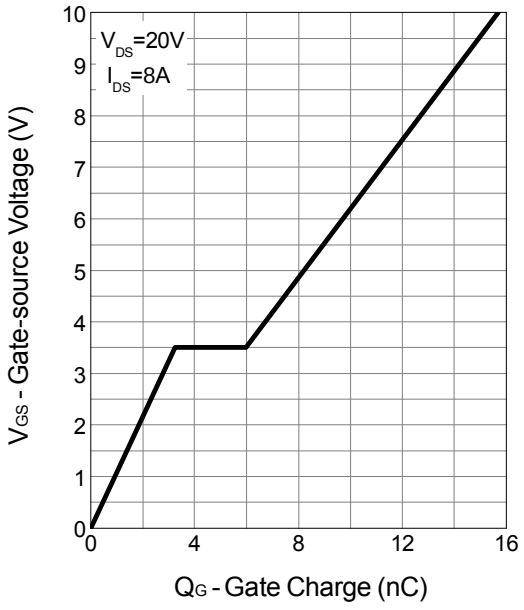
Source-Drain Diode Forward



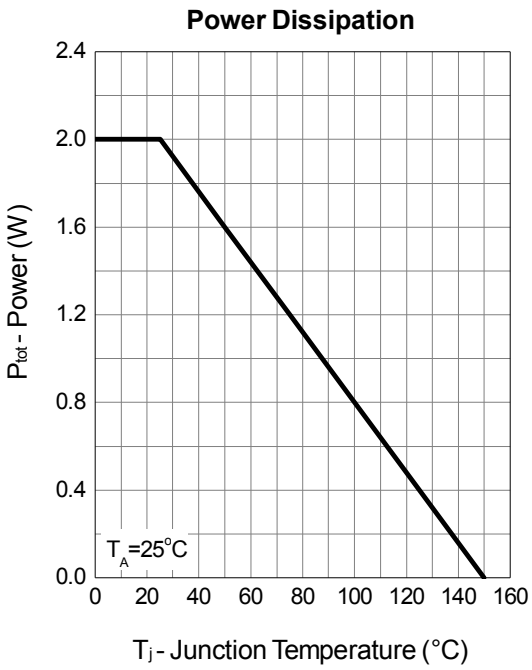
Capacitance

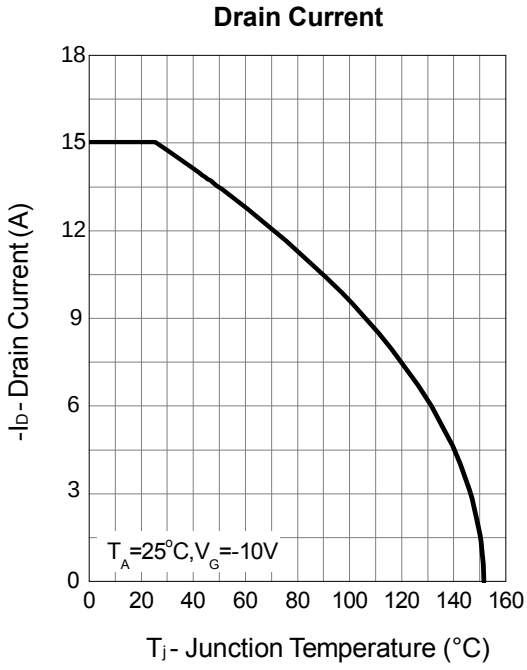


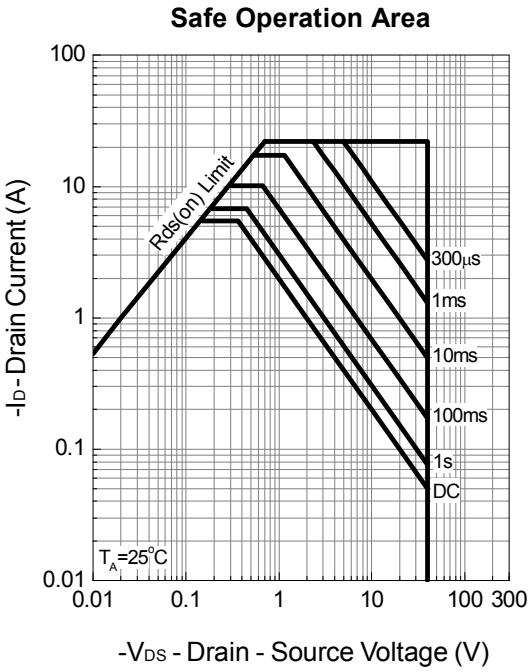
Gate Charge

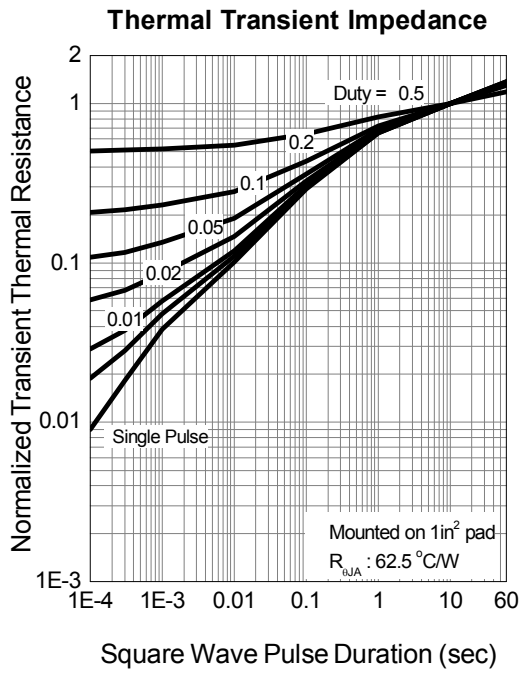


P Channel Typical Operating Characteristics



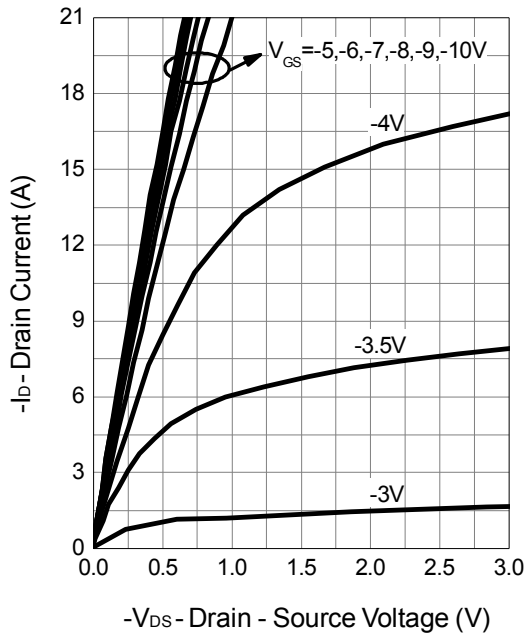




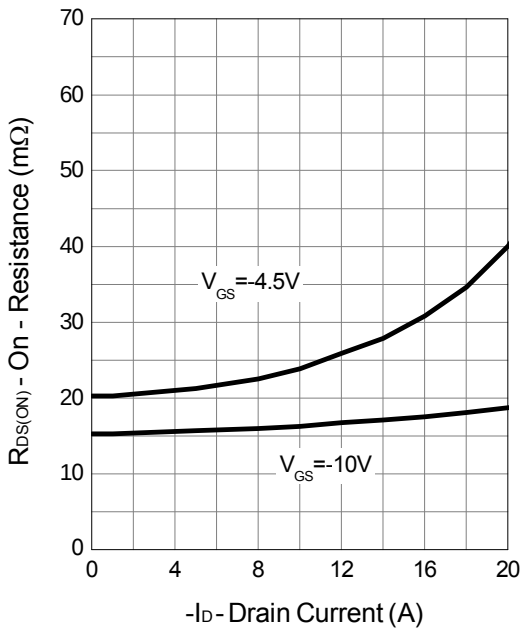


P Channel Typical Operating Characteristics (Cont.)

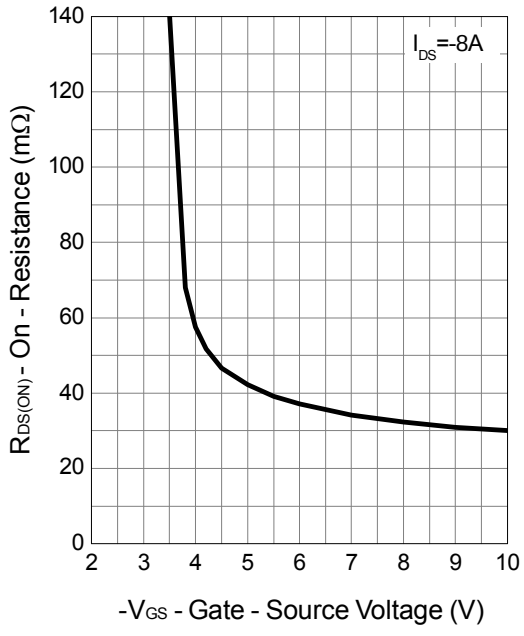
Output Characteristics



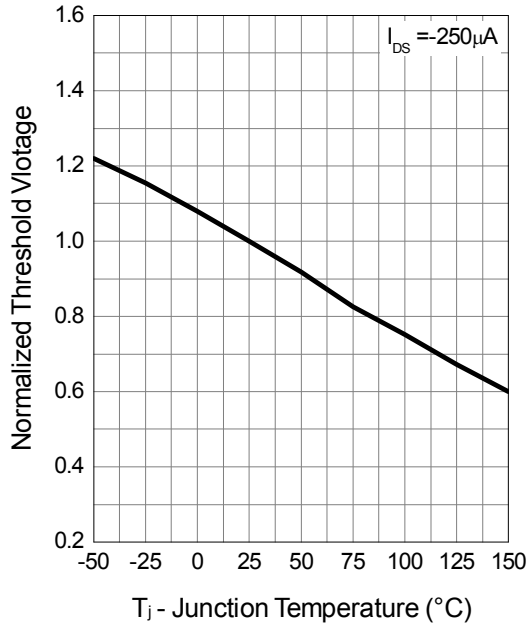
Drain-Source On Resistance



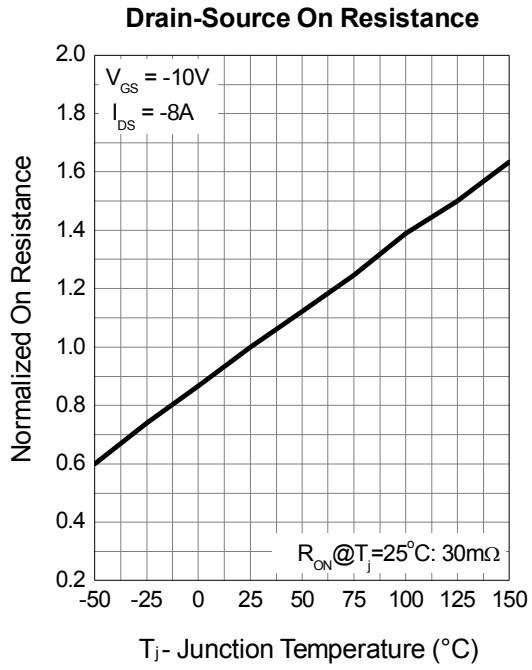
Gate-Source On Resistance

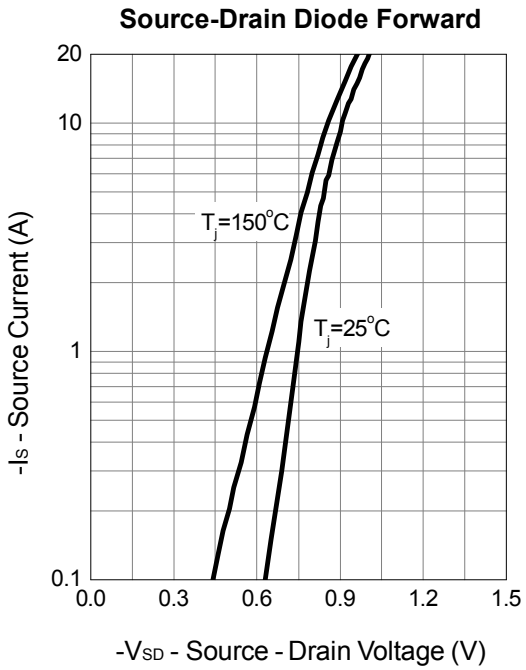


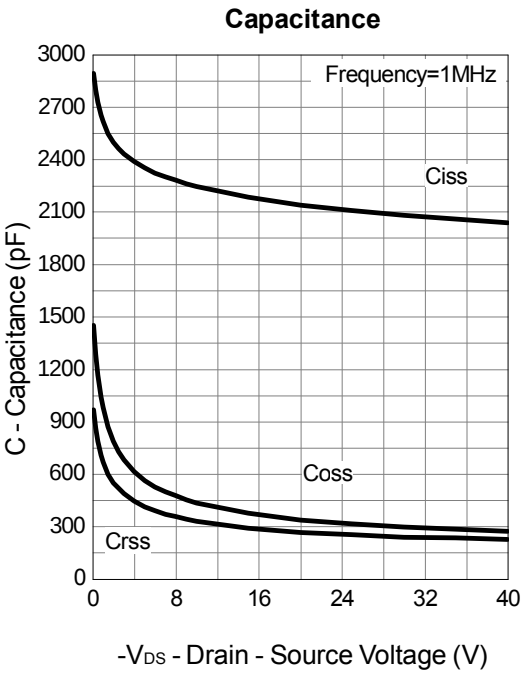
Gate Threshold Voltage

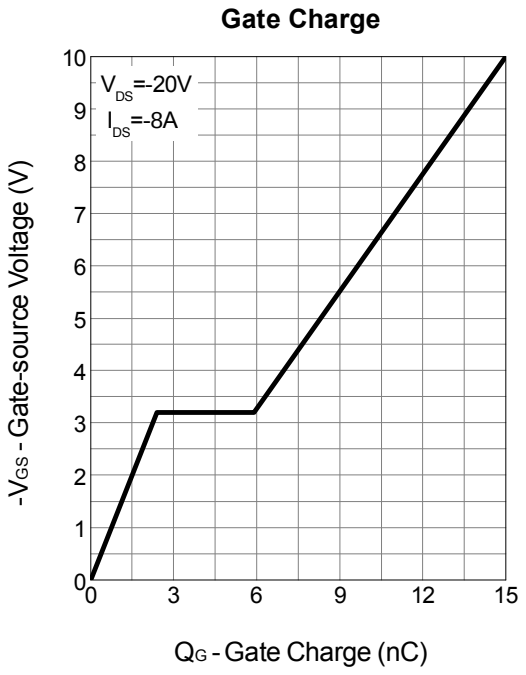


P Channel Typical Operating Characteristics (Cont.)



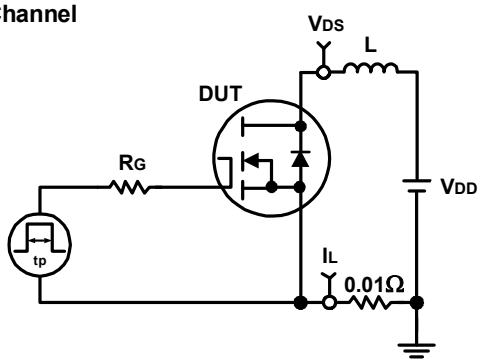


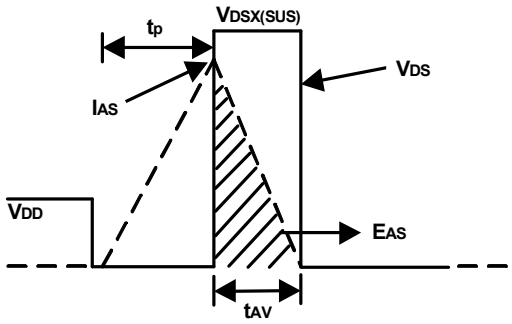




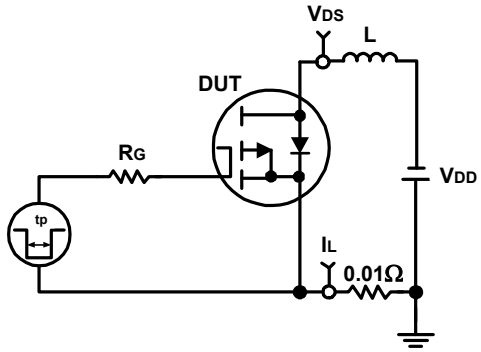
Avalanche Test Circuit and Waveforms

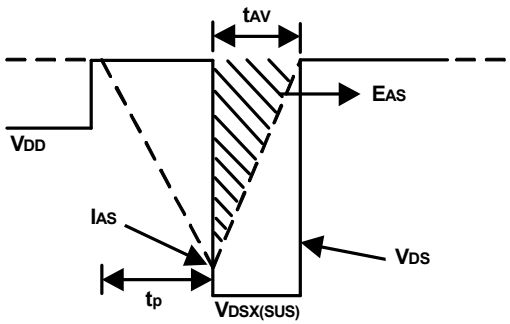
N Channel





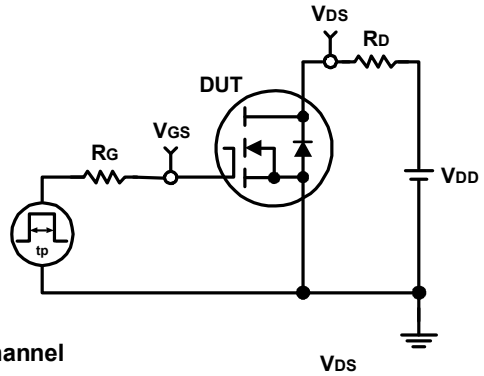
P Channel

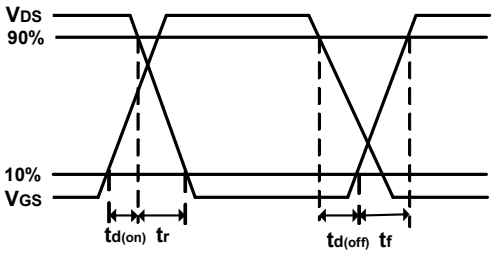




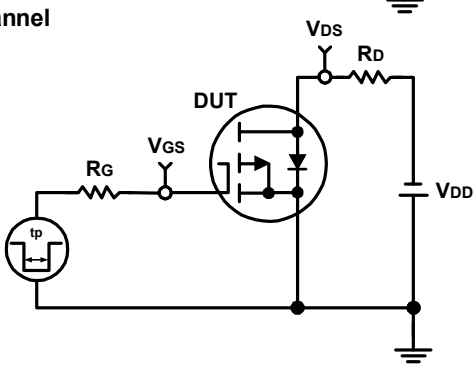
Switching Time Test Circuit and Waveforms

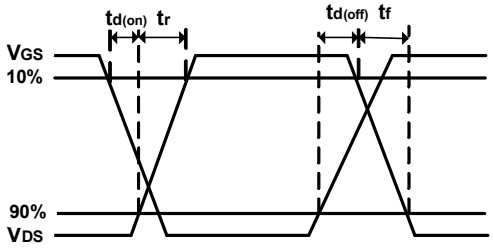
N Channel





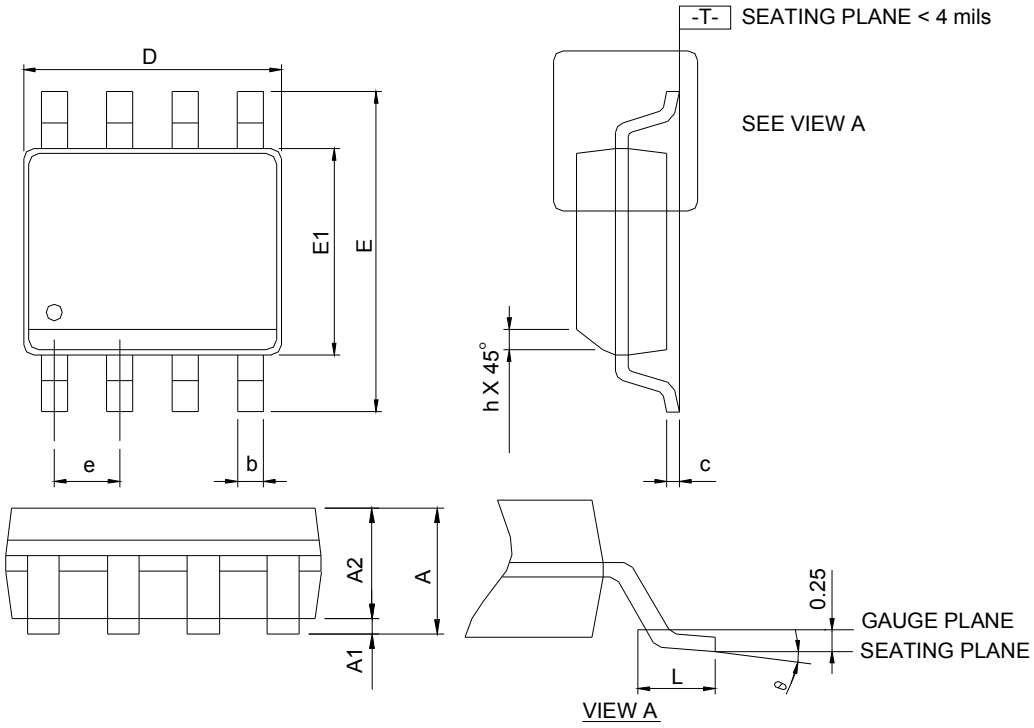
P Channel





Package Information

SOP-8



SYMBOL	SOP-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	1.75	-	0.069
A1	0.10	0.25	0.004	0.010
A2	1.25	-	0.049	-
b	0.31	0.51	0.012	0.020
c	0.17	0.25	0.007	0.010
D	4.80	5.00	0.189	0.197
E	5.80	6.20	0.228	0.244
E1	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
h	0.25	0.50	0.010	0.020
L	0.40	1.27	0.016	0.050
θ	0°	8°	0°	8°

Note: 1. Follow JEDEC MS-012 AA.
2. Dimension D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension E" does not include inter-lead flash or protrusions. Inter-lead flash and protrusions shall not exceed 10 mil per side.

RECOMMENDED LAND PATTERN